



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-03-15
<b>Company Unique ID</b>	NL 008751171801		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Floriana SAN BIAGIO	<b>Representative Title</b>	AMS MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	SS61*UK17ABA	A	ZY1A	2018-03-15
Amount	UoM	Unit type	ST ECOPACK Grade	
79.52	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85x3.9x1.52	8	gull wing	
Comment	61 HSOP 8L .150" PITCH 1.27 EXPOPAD; MDF valid for A5975DTR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	5561*UK17ABA				5999999.0	1000012.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	5.023	mg	supplier	die	Silicon (Si)	7440-21-3		4.792	mg	954012	60262
				supplier	metallization	Aluminium (Al)	7429-90-5		0.032	mg	6371	402
				supplier	metallization	Tungsten (W)	7440-33-7		0.050	mg	9954	629
				supplier	Passivation	Silicon Nitride	12033-89-5		0.008	mg	1593	101
				supplier	Passivation	Silicon Oxide	7631-86-9		0.074	mg	14732	931
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.003	mg	597	38
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.024	mg	4778	302
				supplier	glass coating	Glass; Silicon Dioxide	7631-86-9		0.003	mg	597	38
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.037	mg	7366	465
				Leadframe	M-004 Copper and its alloys	31.386	mg	supplier	alloy	Copper (Cu)	7440-50-8	
supplier	alloy	Iron (Fe)	7439-89-6						0.725	mg	23099	9117
supplier	alloy	Zinc (Zn)	7440-66-6						0.037	mg	1179	465
supplier	alloy	Phosphorus (P)	12185-10-3						0.010	mg	319	126
supplier	metallization	Silver(Ag)	7440-22-4						0.540	mg	17205	6791
Die attach	M-015 Other organic materials	0.635	mg	supplier	glue	Epoxy resin A	9003-36-5		0.044	mg	69291	553
				supplier	glue	Epoxy resin B	68475-94-5		0.025	mg	39370	314
				supplier	glue	Silver(Ag)	7440-22-4		0.491	mg	773228	6175
				supplier	glue	Lactone	96-48-0		0.025	mg	39370	314
				supplier	glue	Polyoxypropylenediamine	9046-10-0		0.025	mg	39370	314
				supplier	glue	2,6-Diglycidyl phenyl allyl ether oligomer	Proprietary		0.025	mg	39370	314
Bonding wires	M-008 Precious metals	0.254	mg	supplier	wire	Gold (Au)	7440-57-5		0.254	mg	1000000	3194
Encapsulation	M-015 Other organic materials	40.911	mg	supplier	mold compound	Epoxy Resin	29690-82-2		3.068	mg	74992	38581
				supplier	mold compound	Silica fused (SiO2)	60676-86-0		35.184	mg	860013	442455
				supplier	mold compound	Phenol Resin	25068-38-6		1.636	mg	39989	20573
				supplier	mold compound	Carbon Black	1333-86-4		0.205	mg	5011	2578
supplier	mold compound	Epoxy, Cresol Novolac	29690-82-2		0.818	mg	19995	10287				
connections coating	M-011 Other inorganic materials	1.312	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.312	mg	1000000	16499